

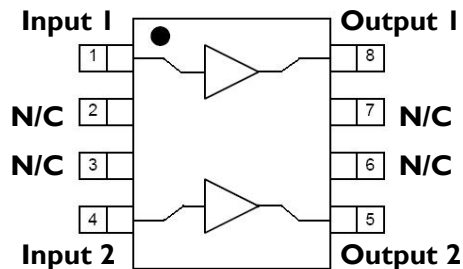
# 0.05-4.0 GHz Dual High Dynamic Range Amplifier



January 2010 - Rev 12-Jan-10

## Features

- ✕ Matched Pair of Amplifiers for Optimum Balanced Design
- ✕ 0.05 to 4.0 GHz Frequency Range
- ✕ 44 dBm Output IP3 (Balanced configuration)
- ✕ 41 dBm Output IP3 (Single-ended configuration)
- ✕ 13 dB Gain @ 2 GHz
- ✕ 22.5 dBm P1dBm
- ✕ 2.1 dB Noise Figure
- ✕ RoHS Compliant SOIC-8 Package
- ✕ Single Positive Supply
- ✕ +3V to +5V Voltage Rail



Backside slug is source GND

## General Description

The XG1001-SA is a dual high dynamic range amplifier designed for applications operation within the 0.05 to 4.0 GHz frequency range. Co-located matched amplifiers are assembled in an RoHS compliant SOIC-8 package. The XG1001-SA is an ideal solution for implementing balanced or push-pull designs. The amplifier can also be used for dual-band operation where single-ended design is used for each band. The amplifier has the flexibility of being optimized for a number of wireless applications. The combination of low noise figure and high IP3 at the same bias point make it an ideal transmit or receive solution when used in applications including CATV operating from 50 to 850 MHz, cellular and PCS (personal communications service) operating from 0.8 to 2.2 GHz; MMDS (multichannel multipoint distribution systems) operating from 2.2 to 2.7 GHz; and WLAN (wireless LAN) operation at 2.4 GHz. All devices are 100% RF and DC tested.

## Absolute Maximum Ratings

Supply Voltage	+6.0 V
RF Input Power*	+20 dBm
Storage Temperature (Tstg)	-55 °C to +125 °C
Junction Temperature	150 °C
Operating Temperature	-40 °C to +85 °C
Thermal Resistance	27 °C/W

Operation of this device above any of these parameters may cause damage.  
\*Operation with more than 10 dBm of input power may cause 2 dB degradation in OIP3 performance.

## Typical Parameters

Parameter	Typical			Units
	0.9	2	2.4	
Frequency Range	0.9	2	2.4	GHz
Gain	14.5	13	12	dB
Input Return Loss	-13	-14.5	-20	dB
Output Return Loss	-16	-15.4	-11	dB
Output IP3	42	41	40.5	dBm
Noise Figure	2.1	2.1	2.6	dB
Output P1dB	+22.5	+22.5	+22.5	dBm

Typical values reflect performance in recommended application circuit @ +5V.

## Electrical Characteristics (T = 25°C)

Unless otherwise specified, the following specifications are guaranteed at room temperature in a Mimix fixture.

Parameter	Condition	Units	Min.	Typ.	Max.
Frequency Range		GHz	0.05		4.0
Gain	Externally Matched	dB	11.5	13	
Input Return Loss	Externally Matched	dB		-10	
Output Return Loss	Externally Matched	dB		-10	
Output IP3		dBm	38	41	
Noise Figure		dB		2.1	
Output P1dB		dBm		22.5	
Operating Current Range		mA	120	160	200
Supply Voltage		V		5.0	

Notes:

1. T = 25°C, Frequency = 2 GHz, 50 Ohm system.
2. Each single ended amplifier is tested separately.
3. OIP3 is measured with two tones at output power of 5 dBm/ tone separated by 10 MHz.
4. Slight performance degradation is expected over temperature.

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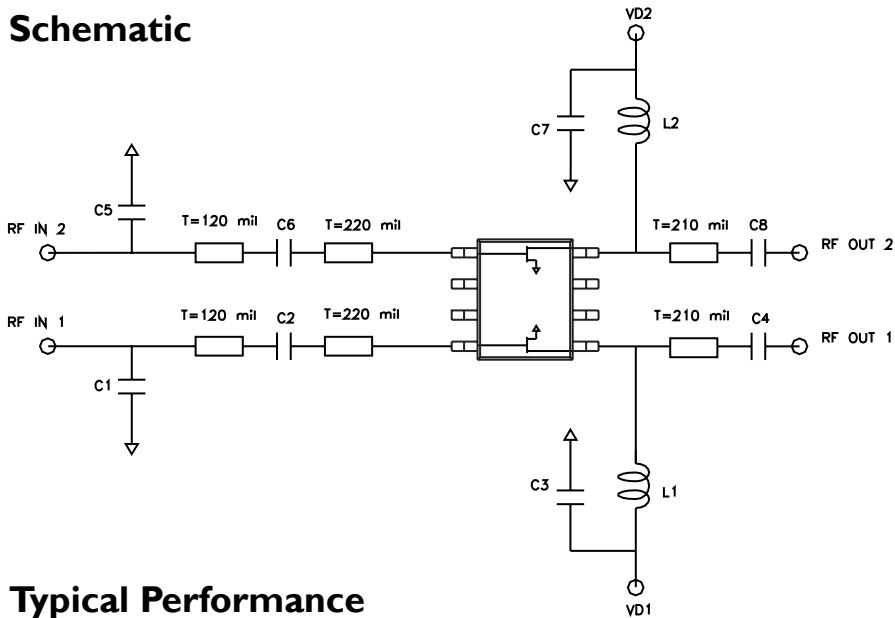
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# 0.05-4.0 GHz Dual High Dynamic Range Amplifier

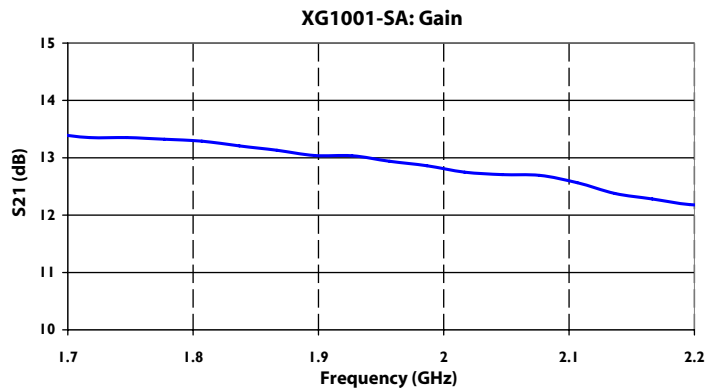
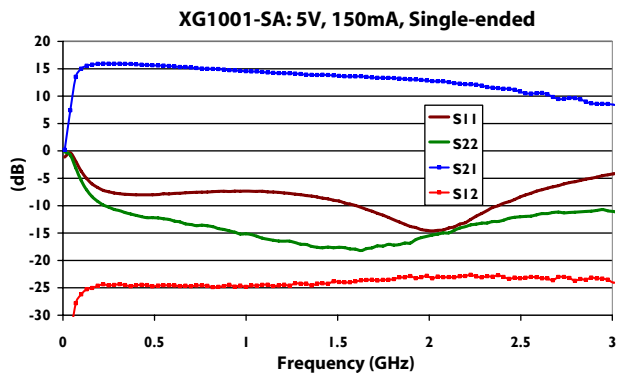
January 2010 - Rev 12-Jan-10

**XG1001-SA**  
RoHS

## Application Circuit @ 1.9 GHz ~ 2.1 GHz: Schematic



## Typical Performance



Parameter	Typ	Typ	Typ	Units
Frequency Range	1.9	2.0	2.1	GHz
Gain	13	12.8	12.0	dB
Input Return Loss	-14	-14.5	-14.0	dB
Output Return Loss	-17	-15.4	-15	dB
Output IP3	40.5	40.1	40.0	dBm
Noise Figure	2.2	2.2	2.2	dB
Output P1 dB	22.5	22.5	22.6	dBm

## Components

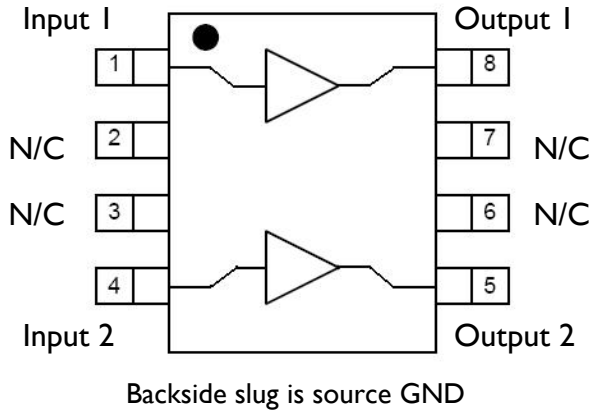
Ref Designator	Value	Size
C2, C4, C6, C8	100 pf	0402
C1, C5	1.0 pf	0603
C3, C7	1000 pf	0805
L1, L2	47 nH	0805

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May 2010 Rev 1.2

XG1001-SA  
RoHS

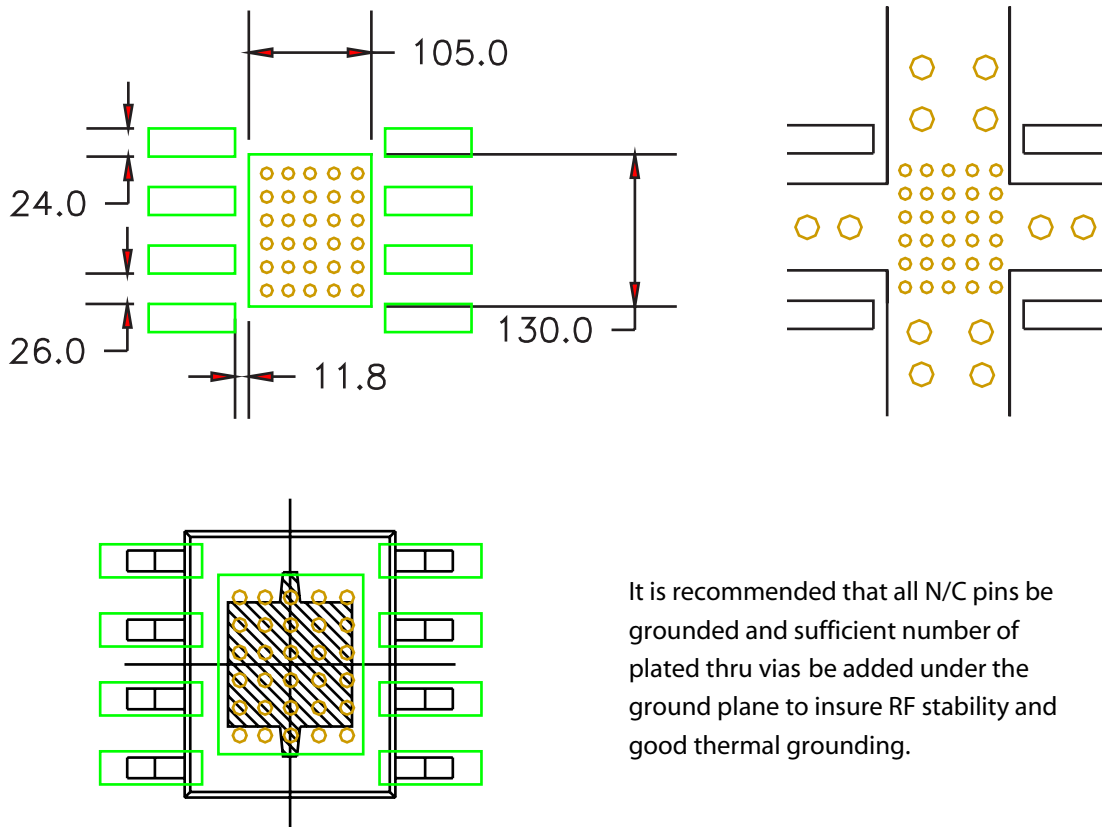
## Functional Block Diagram



## Pin Out Detail

Pin	Function	Description
1	IN 1	Amplifier 1 RF input
4	IN 2	Amplifier 2 RF input
5	OUT 2	Amplifier 1 RF Output
8	OUT 1	Amplifier 2 RF Output
2,3,6,7	N/C	

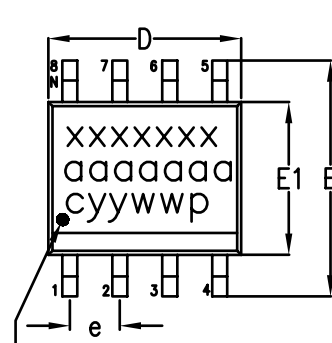
## Land Pattern



# 0.05-4.0 GHz Dual High Dynamic Range Amplifier

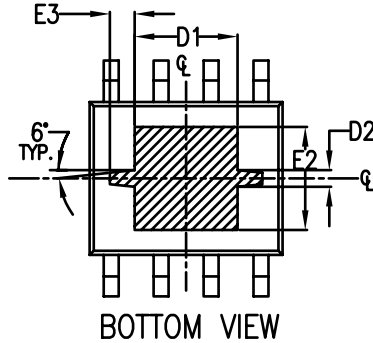
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## Physical Dimensions

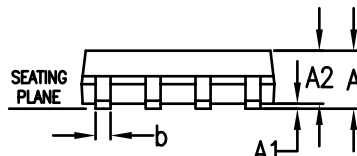


Pin 1 TOP VIEW

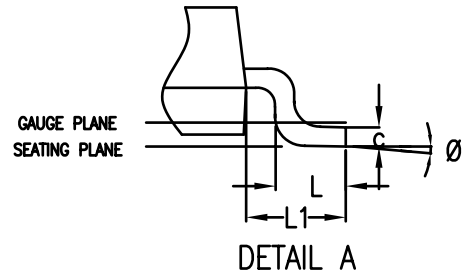
MARKINGS:  
MIMIX PART/MODEL NO.  
WAFER LOT NUMBER  
DATE CODE = yyww  
C = COUNTRY OF ORIGIN  
P = PLATING OPTION



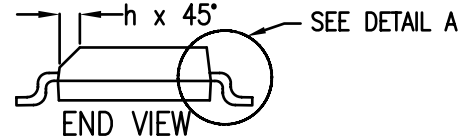
BOTTOM VIEW



SIDE VIEW

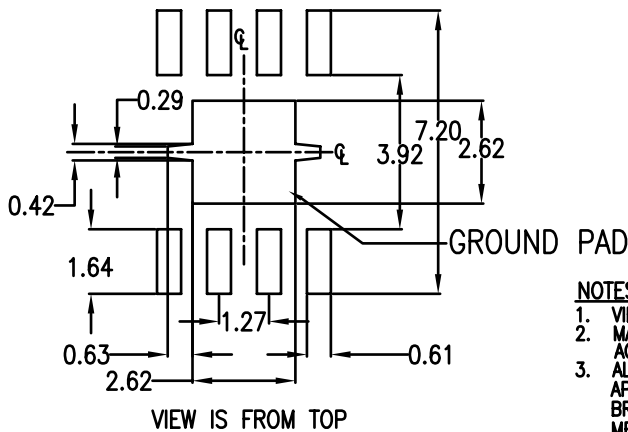


DETAIL A



END VIEW

### GENERIC RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS DIMENSIONS ARE IN MM



VIEW IS FROM TOP

DIMENSIONS ARE IN MM			
SYM	MIN	NOM	MAX
A	1.42	1.47	1.55
A1	0.025	0.102	0.127
A2	1.30	1.37	1.45
b	0.36	0.41	0.51
c	0.18	0.20	0.25
D	4.85	4.90	4.95
D1	2.03	-	2.28
D2	0.13	-	0.38
E1	3.84	3.89	3.94
E2	2.03	-	2.28
E3	0.30	-	0.55
E	5.94	6.10	6.20
e	1.27		
L	0.51	0.69	0.81
L1	1.07	1.12	1.17
Ø	0"	-	8"
h	0.28	0.38	0.48

#### NOTES:

- VIEWS ARE NOT TO SCALE. USE DIMENSIONS AND TABLE.
- MARKINGS ARE FOR ILLUSTRATION PURPOSES ONLY. ACTUAL MARKINGS MAY VARY FOR EACH DEVICE TYPE MODULE.
- ALL INFORMATION CONTAINED HEREIN IS FOR USE WITH MIMIX BROADBAND APPLICATION NOTES AND SPECIFICATION DOCUMENTS FOR GENERIC MIMIX BROADBAND DEVICES. INFORMATION MAY NOT REFLECT SPECIFIC REQUIREMENTS FOR EACH UNIQUE CIRCUIT DESIGN USING THIS PACKAGE TYPE.

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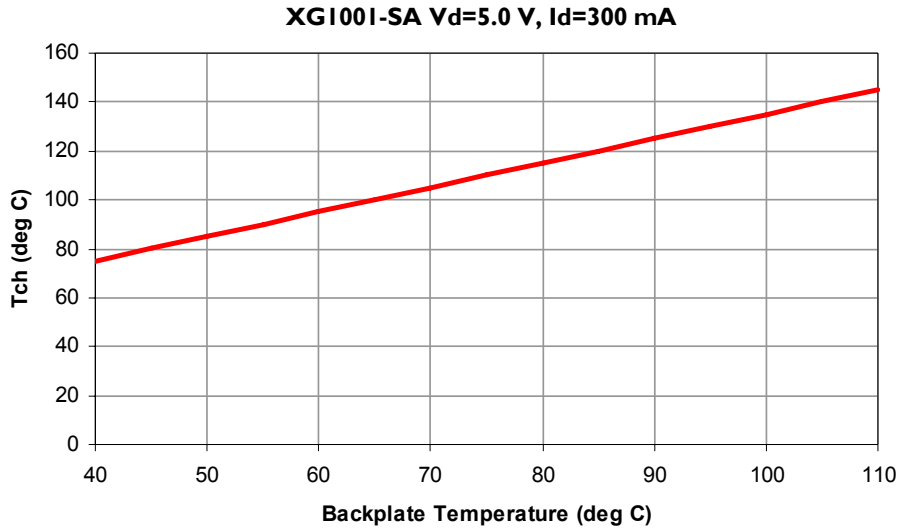
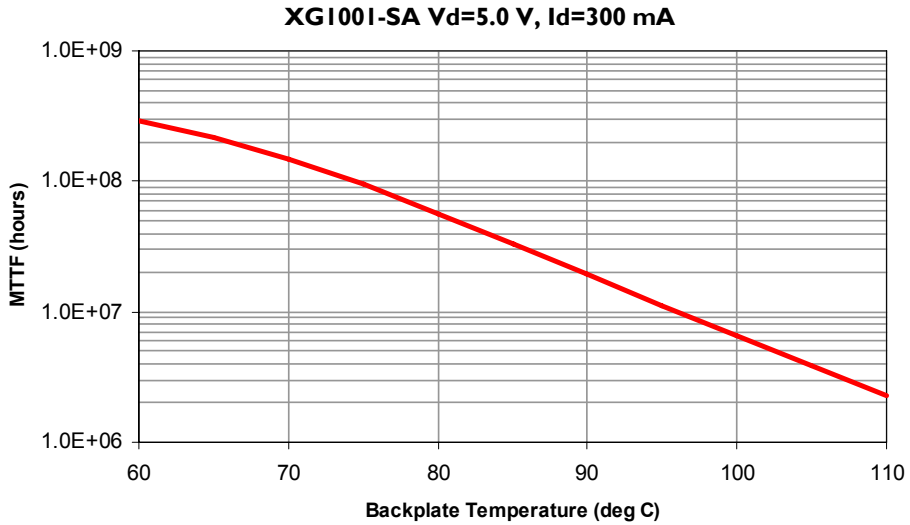
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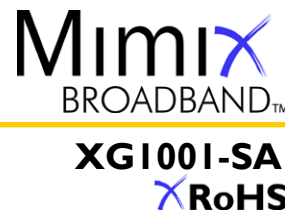
**XGI001-SA**  
RoHS

## MTTF

These numbers were calculated based on accelerated life test information received from the fabrication foundry and measured thermal resistance.



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## Handling and Assembly Information

**CAUTION!** - Mimix Broadband MMIC Products contain gallium arsenide (GaAs) which can be hazardous to the human body and the environment. For safety, observe the following procedures:

- Do not ingest.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.

**Life Support Policy** - Mimix Broadband's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President and General Counsel of Mimix Broadband. As used herein: (1) Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user. (2) A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

**Package Attachment** - This packaged product from Mimix Broadband is provided as a rugged surface mount package compatible with high volume solder installation. Care should be taken not to apply heavy pressure to the top or base material to avoid package damage. Vacuum tools or other suitable pick and place equipment may be used to pick and place this part. Care should be taken to ensure that there are no voids or gaps in the solder connection so that good RF, DC and ground connections are maintained. Voids or gaps can eventually lead not only to RF performance degradation, but reduced reliability and life of the product due to thermal stress.

**Mimix Lead-Free RoHS Compliant Program** - Mimix has an active program in place to meet customer and governmental requirements for eliminating lead (Pb) and other environmentally hazardous materials from our products. All Mimix RoHS compliant components are form, fit and functional replacements for their non-RoHS equivalents. Lead plating of our RoHS compliant parts is 100% matte tin (Sn) over copper alloy and is backwards compatible with current standard SnPb low-temperature reflow processes as well as higher temperature (260°C reflow) "Pb Free" processes.

## Ordering Information

### Part Number for Ordering

XG1001-SA-0G00  
XG1001-SA-0G0T

### Description

Matte Tin plated RoHS compliant SOIC-8 surface mount package in bulk quantity  
Matte Tin plated RoHS compliant SOIC-8 surface mount package in tape and reel

PB-XG1001-SA-00A0  
PB-XG1001-SA-00B0  
PB-XG1001-SA-00C0

XG1001-SA Evaluation Board @ 900 MHz  
XG1001-SA Evaluation Board @ 1.9 GHz~2.1 GHz  
XG1001-SA Evaluation Board @ 2.4 GHz

We also offer this product with SnPb (Tin-Lead) or NiPdAu plating. Please contact your regional sales manager for more information regarding different plating types.



Proper ESD procedures should be followed when handling this device.

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